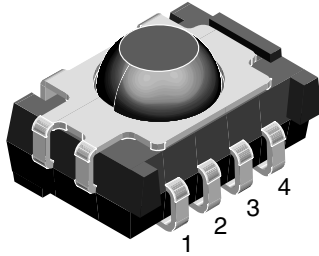


## IR Receiver Modules for Remote Control Systems



16797

### MECHANICAL DATA

#### Pinning:

1 = GND, 2 = GND, 3 =  $V_S$ , 4 = OUT

### FEATURES

- Very low supply current
- Photo detector and preamplifier in one package
- Internal filter for PCM frequency
- Continuous data transmission possible
- Supply voltage: 2.5 V to 5.5 V
- Lead (Pb)-free component
- Insensitive to supply voltage ripple and noise
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC
- Taping available for topview and sideview assembly



### DESCRIPTION

The TSOP351.., TSOP353.. series are miniaturized SMD IR receiver modules for infrared remote control systems. PIN diode and preamplifier are assembled on a lead frame, the epoxy package is designed as IR filter.

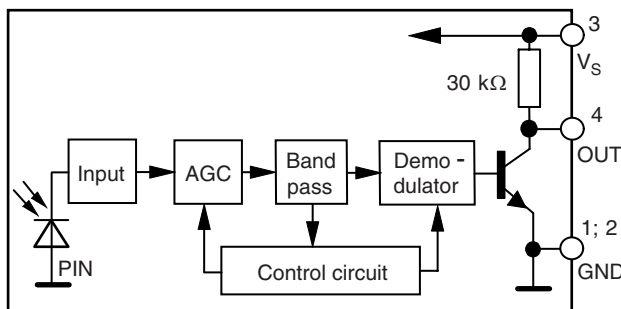
The demodulated output signal can directly be decoded by a microprocessor. The TSOP351.. is compatible with all common IR remote control data formats. The TSOP353.. is optimized to better suppress spurious pulses from energy saving lamps but will also suppress some data signals.

This component has not been qualified according to automotive specifications.

### PARTS TABLE

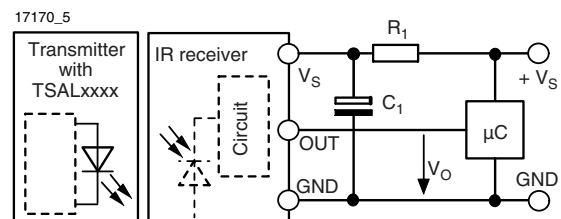
CARRIER FREQUENCY	SHORT BURSTS AND HIGH DATA RATES (AGC1)	NOISY ENVIRONMENTS AND SHORT BURSTS (AGC3)
30 kHz	TSOP35130	TSOP35330
33 kHz	TSOP35133	TSOP35333
36 kHz	TSOP35136	TSOP35336
38 kHz	TSOP35138	TSOP35338
40 kHz	TSOP35140	TSOP35340
56 kHz	TSOP35156	TSOP35356

### BLOCK DIAGRAM



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### APPLICATION CIRCUIT



$R_1$  and  $C_1$  are recommended for protection against EOS. Components should be in the range of  $33 \Omega < R_1 < 1 \text{ k}\Omega$ ,  $C_1 > 0.1 \mu\text{F}$ .

**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Supply voltage (pin 3)		$V_S$	- 0.3 to + 6.0	V
Supply current (pin 3)		$I_S$	3	mA
Output voltage (pin 4)		$V_O$	- 0.3 to ( $V_S + 0.3$ )	V
Output current (pin 4)		$I_O$	5	mA
Junction temperature		$T_j$	100	°C
Storage temperature range		$T_{stg}$	- 40 to + 100	°C
Operating temperature range		$T_{amb}$	- 30 to + 85	°C
Power consumption	$T_{amb} \leq 85$ °C	$P_{tot}$	10	mW

**Note**

(1) Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect the device reliability.

**ELECTRICAL AND OPTICAL CHARACTERISTICS (1)**

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply current (pin 3)	$E_v = 0$ , $V_S = 3.3$ V	$I_{SD}$	0.27	0.35	0.45	mA
	$E_v = 40$ klx, sunlight	$I_{SH}$		0.45		mA
Supply voltage		$V_S$	2.5		5.5	V
Transmission distance	$E_v = 0$ , test signal see fig. 1, IR diode TSAL6200, $I_F = 250$ mA	$d$		45		m
Output voltage low (pin 4)	$I_{OVL} = 0.5$ mA, $E_e = 0.7$ mW/m <sup>2</sup> , test signal see fig. 1	$V_{OVL}$			100	mV
Minimum irradiance	Pulse width tolerance: $t_{pi} - 5/f_0 < t_{po} < t_{pi} + 6/f_0$ , test signal see fig. 1	$E_e \text{ min.}$		0.15	0.35	mW/m <sup>2</sup>
Maximum irradiance	$t_{pi} - 5/f_0 < t_{po} < t_{pi} + 6/f_0$ , test signal see fig. 1	$E_e \text{ max.}$	30			W/m <sup>2</sup>
Directivity	Angle of half transmission distance	$\phi_{1/2}$		$\pm 50$		deg

**Note**

(1)  $T_{amb} = 25$  °C, unless otherwise specified

**TYPICAL CHARACTERISTICS**

$T_{amb} = 25$  °C, unless otherwise specified

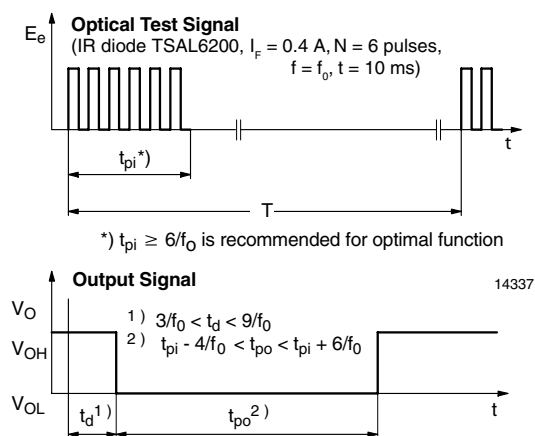


Fig. 1 - Output Function

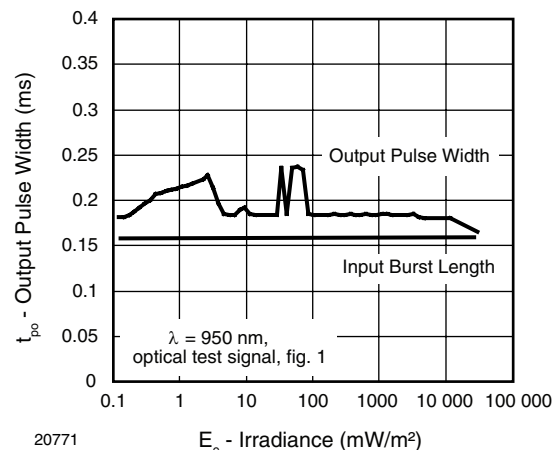


Fig. 2 - Pulse Length and Sensitivity in Dark Ambient

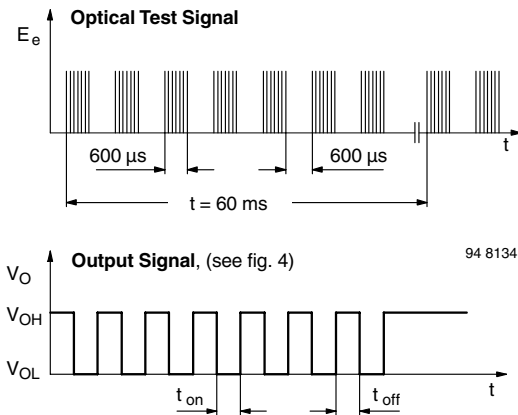


Fig. 3 - Output Function

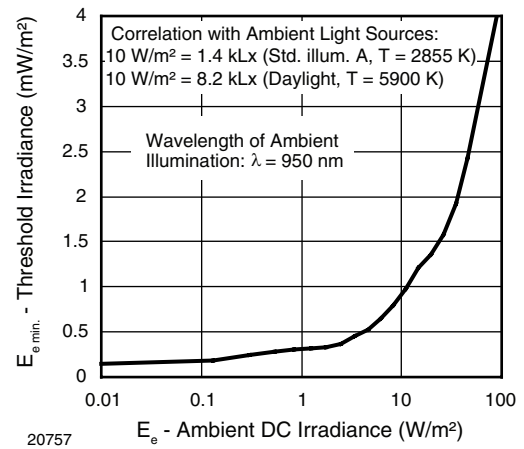


Fig. 6 - Sensitivity in Bright Ambient

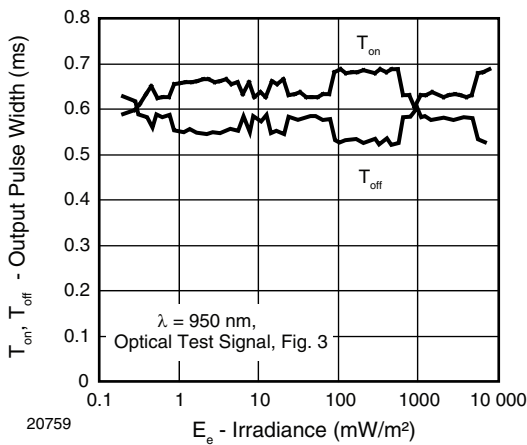


Fig. 4 - Output Pulse Diagram

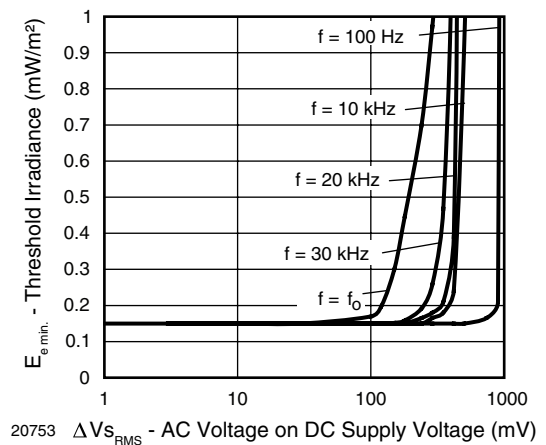


Fig. 7 - Sensitivity vs. Supply Voltage Disturbances

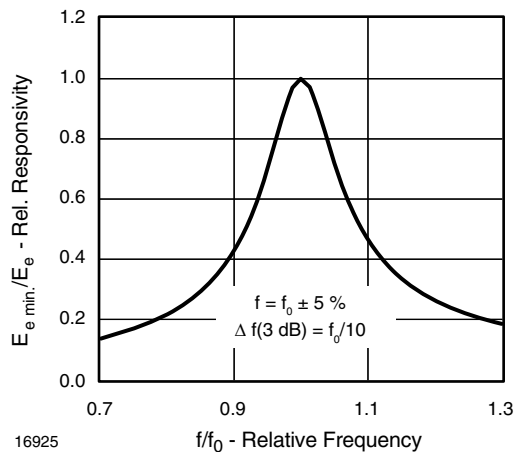


Fig. 5 - Frequency Dependence of Responsivity

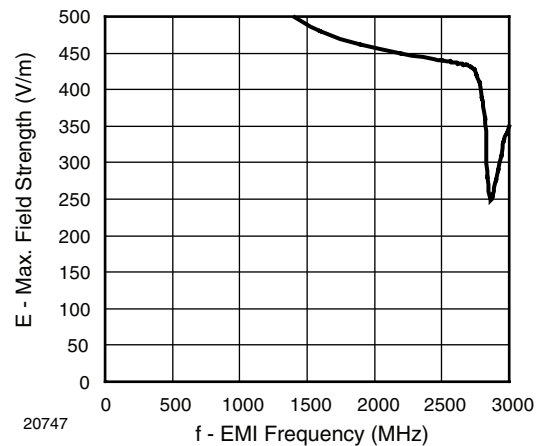


Fig. 8 - Sensitivity vs. Electric Field Disturbances

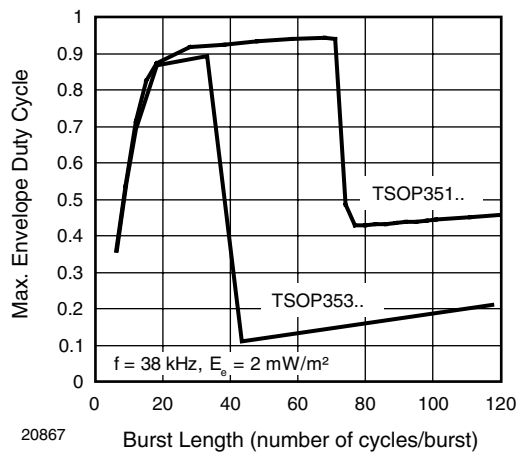


Fig. 9 - Max. Envelope Duty Cycle vs. Burstlength

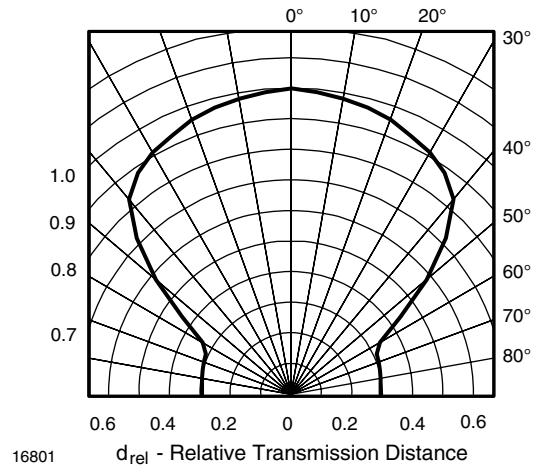


Fig. 12 - Directivity

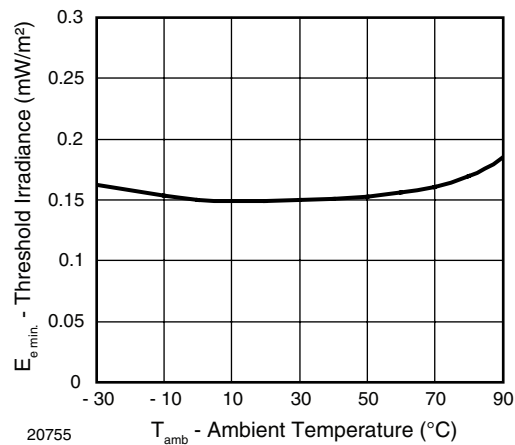


Fig. 10 - Sensitivity vs. Ambient Temperature

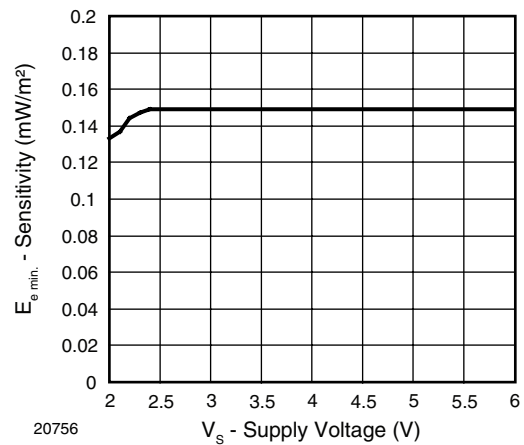


Fig. 13 - Sensitivity vs. Supply Voltage

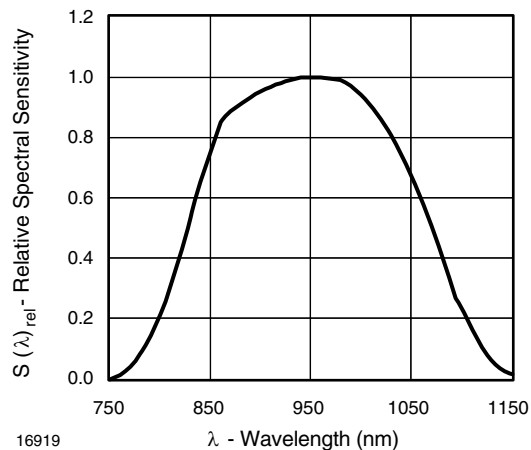


Fig. 11 - Relative Spectral Sensitivity vs. Wavelength



### SUITABLE DATA FORMAT

The TSOP351.., TSOP353.. series is designed to suppress spurious output pulses due to noise or disturbance signals. Data and disturbance signals can be distinguished by the devices according to carrier frequency, burst length and envelope duty cycle. The data signal should be close to the band-pass center frequency (e.g. 38 kHz) and fulfill the conditions in the table below.

When a data signal is applied to the TSOP351.., TSOP353.. in the presence of a disturbance signal, the sensitivity of the receiver is reduced to insure that no spurious pulses are present at the output. Some examples of disturbance signals which are suppressed are:

- DC light (e.g. from tungsten bulb or sunlight)
- Continuous signals at any frequency
- Strongly or noise from fluorescent lamps with electronic ballasts

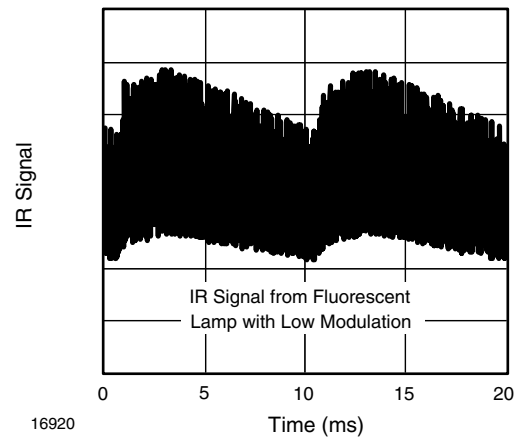


Fig. 14 - IR Signal from Fluorescent Lamp with Low Modulation

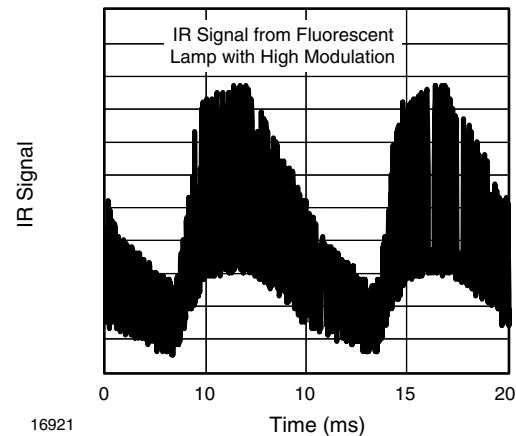


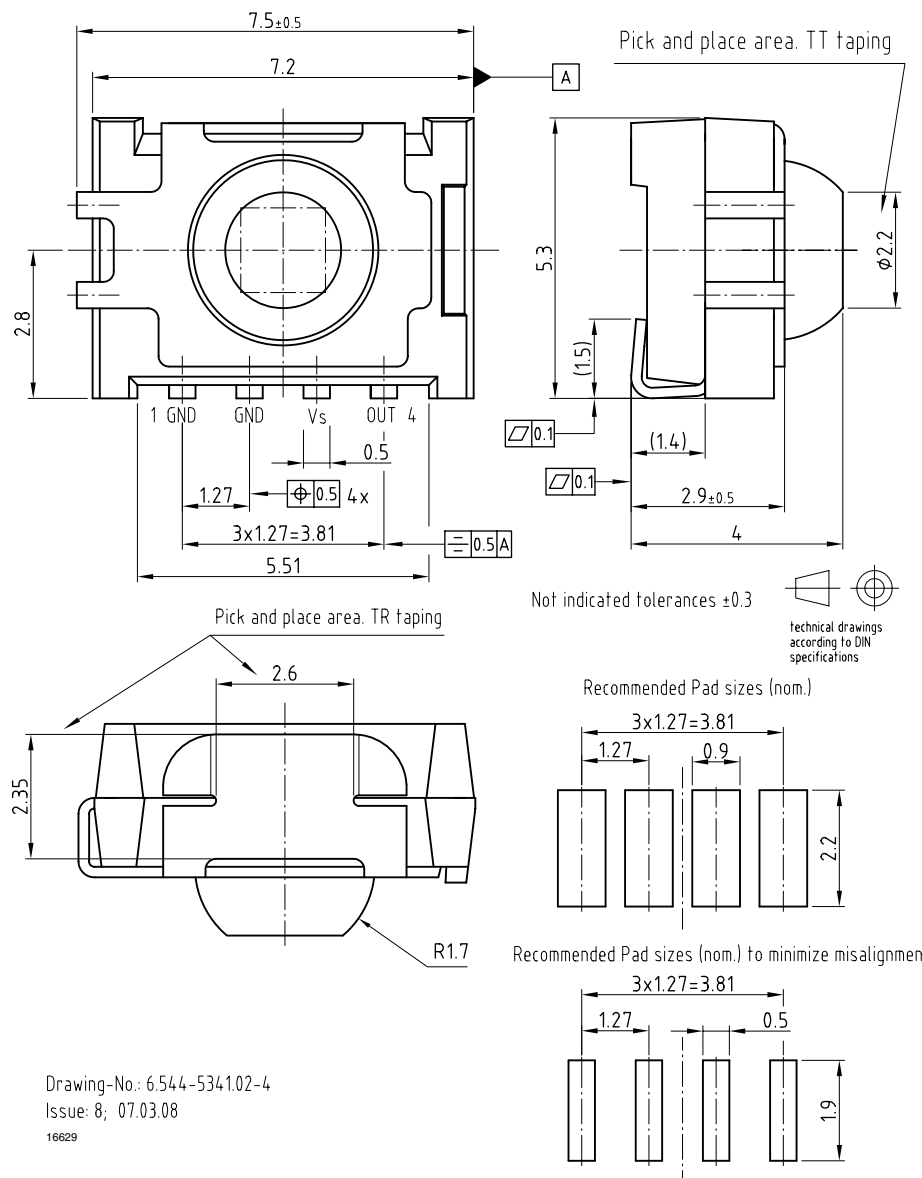
Fig. 15 - IR Signal from Fluorescent Lamp with High Modulation

	TSOP351..	TSOP353..
Minimum burst length	6 cycles/burst	6 cycles/burst
After each burst of length a minimum gap time is required of	6 to 70 cycles ≥ 10 cycles	6 to 35 cycles ≥ 10 cycles
For bursts greater than a minimum gap time in the data stream is needed of	70 cycles > 1.2 x burst length	35 cycles > 6 x burst length
Maximum number of continuous short bursts/second	2000	2000
Compatible to NEC code	yes	yes
Compatible to RC5/RC6 code	yes	yes
Compatible to Sony code	yes	no
Compatible to RCMM code	yes	yes
Compatible to r-step code	yes	yes
Compatible to XMP code	yes	yes
Suppression of interference from fluorescent lamps	Common disturbance signals are suppressed (Example: signal pattern of fig. 14)	Even critical disturbance signals are suppressed (Example: signal pattern of fig. 14 and fig. 15)

#### Note

For data formats with long bursts (more than 10 carrier cycles) please see the datasheet for TSOP352.., TSOP354..

### PACKAGE DIMENSIONS in millimeters



## ASSEMBLY INSTRUCTIONS

## Reflow Soldering

- Reflow soldering must be done within 72 h while stored under a max. temperature of 30 °C, 60 % RH after opening the dry pack envelope
- Set the furnace temperatures for pre-heating and heating in accordance with the reflow temperature profile as shown in the diagram. Exercise extreme care to keep the maximum temperature below 260 °C. The temperature shown in the profile means the temperature at the device surface. Since there is a temperature difference between the component and the circuit board, it should be verified

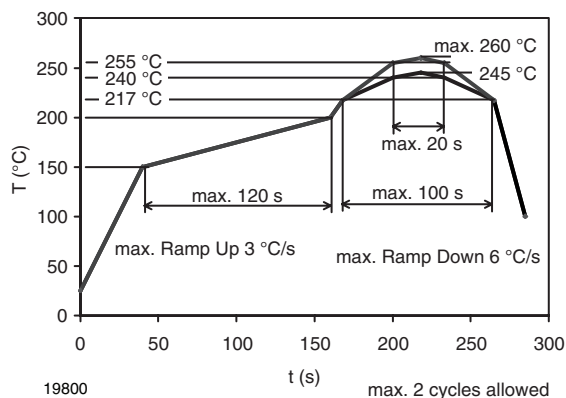
that the temperature of the device is accurately being measured

- Handling after reflow should be done only after the work surface has been cooled off

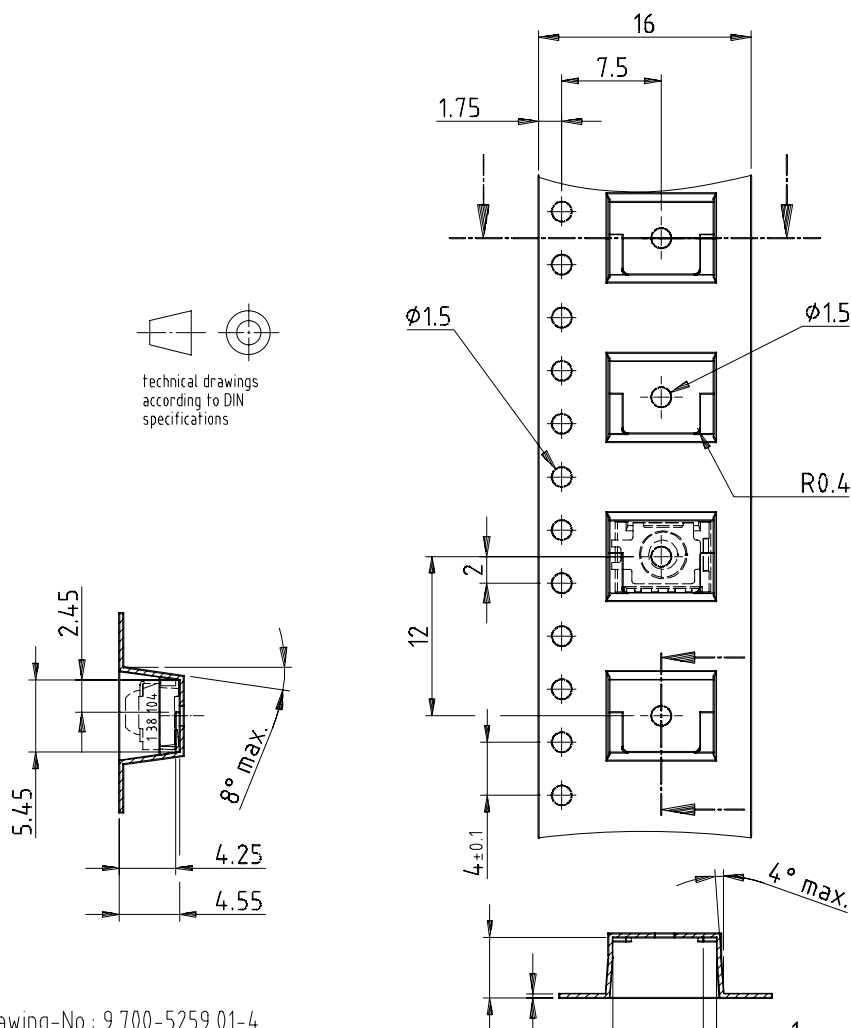
## Manual Soldering

- Use a soldering iron of 25 W or less. Adjust the temperature of the soldering iron below 300 °C
- Finish soldering within 3 s
- Handle products only after the temperature has cooled off.

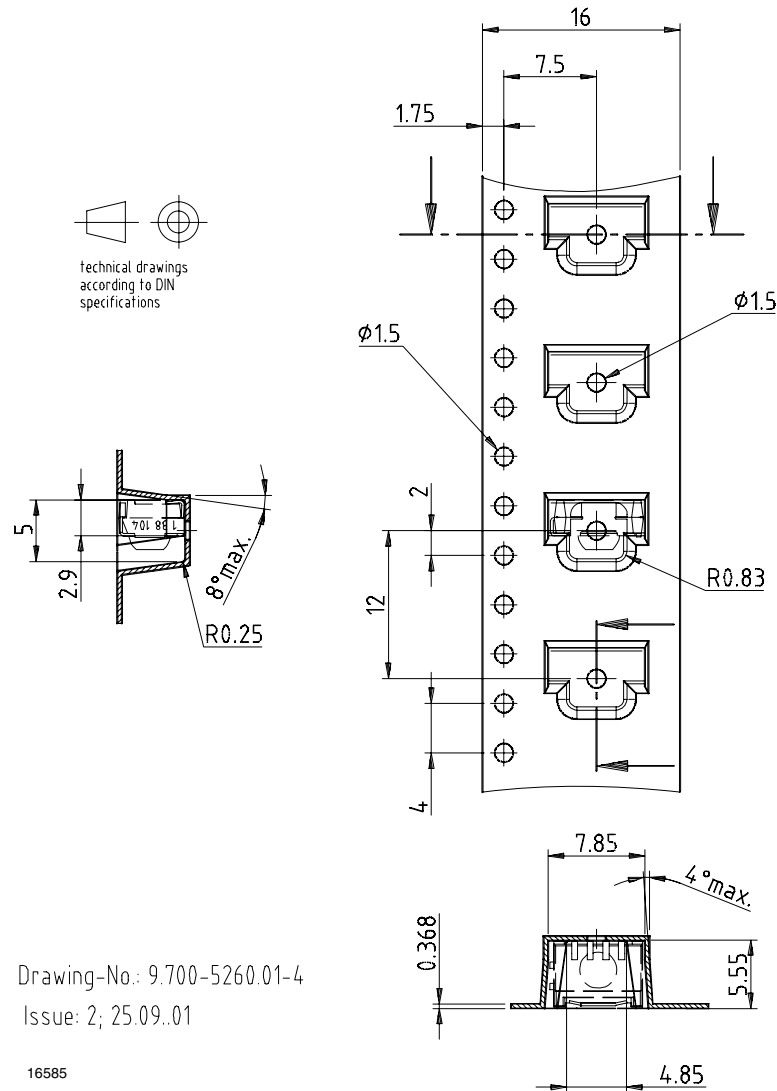
## VISHAY LEAD (Pb)-FREE REFLOW SOLDER PROFILE



**TAPING VERSION TSOP..TT** Dimensions in millimeters

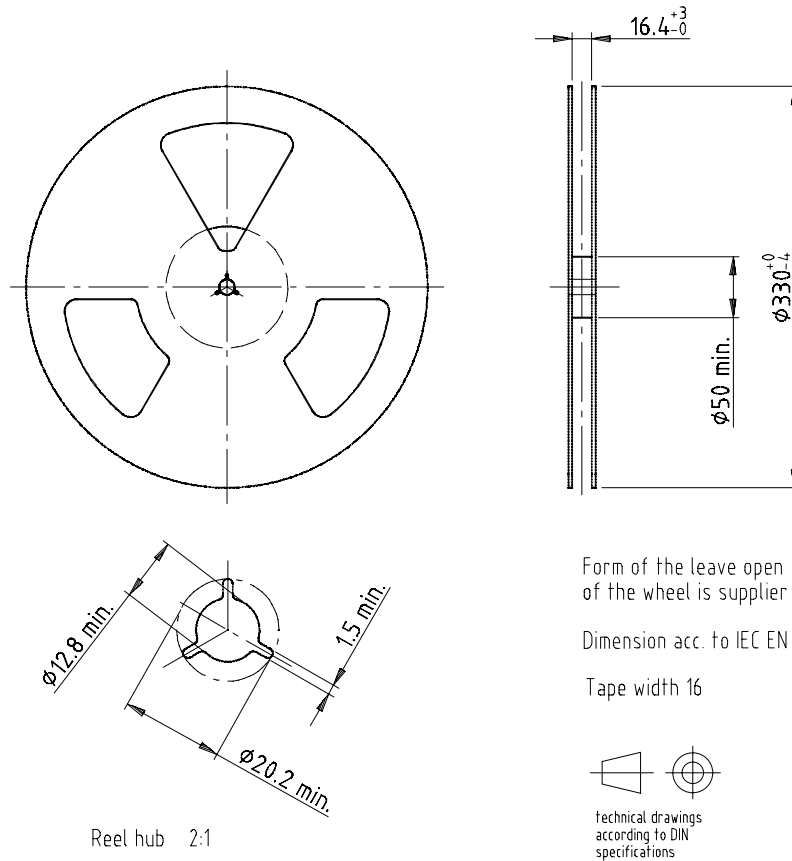


## TAPING VERSION TSOP..TR Dimensions in millimeters





### REEL DIMENSIONS in millimeters



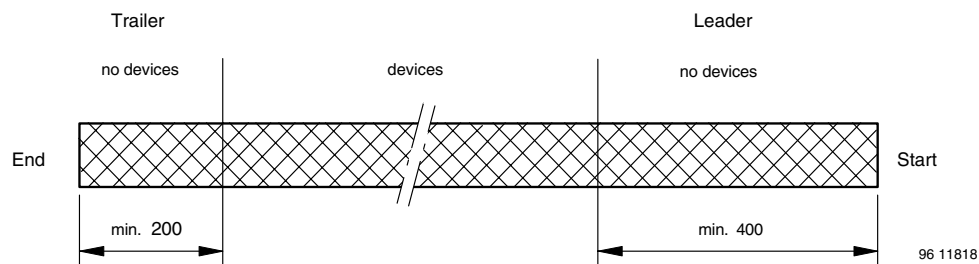
Drawing refers to following types: Reel for blister carrier tape Version B

Drawing-No.: 9.800-5052.V2-4

Issue: 1; 07.05.02

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### LEADER AND TRAILER Dimensions in millimeters



### COVER TAPE PEEL STRENGTH

According to DIN EN 60286-3

0.1 to 1.3 N

300  $\pm$  10 mm/min.

165° to 180° peel angle

### LABEL

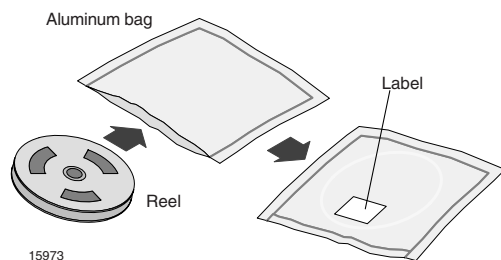
#### Standard bar code labels for finished goods

The standard bar code labels are product labels and used for identification of goods. The finished goods are packed in final packing area. The standard packing units are labeled with standard bar code labels before transported as finished goods to warehouses. The labels are on each packing unit and contain Vishay Semiconductor GmbH specific data.

VISHAY SEMICONDUCTOR GMBH STANDARD BAR CODE PRODUCT LABEL (Finished Goods)		
PLAIN WRITTING	ABBREVIATION	LENGTH
Item-description	-	18
Item-number	INO	8
Selection-code	SEL	3
LOT-/serial-number	BATCH	10
Data-code	COD	3 (YWW)
Plant-code	PTC	2
Quantity	QTY	8
Accepted by	ACC	-
Packed by	PCK	-
Mixed code indicator	MIXED CODE	-
Origin	xxxxxxx+	Company logo
LONG BAR CODE TOP	TYPE	LENGTH
Item-number	N	8
Plant-code	N	2
Sequence-number	X	3
Quantity	N	8
Total length	-	21
SHORT BAR CODE BOTTOM	TYPE	LENGTH
Selection-code	X	3
Data-code	N	3
Batch-number	X	10
Filter	-	1
Total length	-	17

## DRY PACKING

The reel is packed in an anti-humidity bag to protect the devices from absorbing moisture during transportation and storage.



## FINAL PACKING

The sealed reel is packed into a cardboard box. A secondary cardboard box is used for shipping purposes.

## RECOMMENDED METHOD OF STORAGE

Dry box storage is recommended as soon as the aluminum bag has been opened to prevent moisture absorption. The following conditions should be observed, if dry boxes are not available:

- Storage temperature 10 °C to 30 °C
- Storage humidity ≤ 60 % RH max.

After more than 72 h under these conditions moisture content will be too high for reflow soldering.


In case of moisture absorption, the devices will recover to the former condition by drying under the following condition:

192 h at 40 °C + 5 °C/ - 0 °C and < 5 % RH (dry air/nitrogen) or

96 h at 60 °C + 5 °C and < 5 % RH for all device containers or 24 h at 125 °C + 5 °C not suitable for reel or tubes.

An EIA JEDEC standard JESD22-A112 level 4 label is included on all dry bags.



	<b>CAUTION</b> This bag contains MOISTURE-SENSITIVE DEVICES	I. E. V. E. L. <b>4</b>
<p>1. Shelf life in sealed bag 12 months at <math>&lt;40^{\circ}\text{C}</math> and <math>&lt;90\%</math> relative humidity (RH)</p> <p>2. After this bag is opened devices that will be subjected to infrared reflow, vapor-phase reflow, or equivalent processing (peak package body temp. <math>220^{\circ}\text{C}</math>) must be:</p> <p>2a. Mounted within <b>72 hours</b> at factory condition of <math>\leq 30^{\circ}\text{C}/60\%\text{RH}</math> or</p> <p>2b. Stored at <math>\leq 20\%\text{RH}</math>.</p> <p>3. Devices require baking before mounting if: Humidity Indicator Card is <math>&gt;20\%</math> when read at <math>23^{\circ}\text{C} \pm 5^{\circ}\text{C}</math> or 2a or 2b is not met.</p> <p>4. If baking is required, devices may be baked for: <b>192 hours</b> at <math>40^{\circ}\text{C} \pm 5^{\circ}\text{C}/0^{\circ}\text{C}</math> and <math>&lt;5\%\text{RH}</math> (dry air/nitrogen) or <b>96 hours</b> at <math>60 \pm 5^{\circ}\text{C}</math> and <math>&lt;5\%\text{RH}</math> For all device containers or <b>24 hours</b> at <math>125 \pm 5^{\circ}\text{C}</math> Not suitable for reels or tubes</p> <p>Bag Seal Date: _____ (If blank, see bar code label)</p> <p>Note: I.E.V.E.L. defined by EIA JEDEC Standard JESD22-A112</p>		

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Example of JESD22-A112 level 4 label

### ESD PRECAUTION

Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the antistatic shielding bag. Electro-static sensitive devices warning labels are on the packaging.

### VISHAY SEMICONDUCTORS STANDARD BAR CODE LABELS

The Vishay Semiconductors standard bar code labels are printed at final packing areas. The labels are on each packing unit and contain Vishay Semiconductors specific data.

				VISHAY	
<b>TSOP6238TR</b>				ORIGIN PHILIPPINES	
					
PTC	SEL	DATE	CODE (4M)	BATCH NO.	
19		2002/16	5		
				<b>1120</b> PCS	

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## **OZONE DEPLETING SUBSTANCES POLICY STATEMENT**

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively.
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA.
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design  
and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany



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